# **Technical Exposure:**

Operating System : Windows 9x/ 20xx / XP, Linux.
Application : Ms-Office 2000, Office XP & 9x.

Layout Tools : Cadence Allegro PCB Editor, Cad soft Eagle, OrCad Layout Plus,

Mentor Graphics Pads Layout, DipTrace, AutoCAD, KiCad, Altium Designer.

Schematic tool : OrCAD /Allegro Capture, Pads Logic, Eagle, DipTrace, KiCad, Altium.

■ DFM Tool : ECAM – CAM-350 7.5.1, Valor.

# **PCB Skills:**

 PCB design, layout and packaging of high-speed, high-density, Mixed Technology Analog / Digital signals & RF signals, Flex, Rigid board, Commercial, Application Boards, based on client requirement and Quality Inspection of the design.

- Designed multilayered boards up to 36 layers.
- Board Design for EMI/EMC, ESD and THERMAL consideration boards.
- Designed with BGA, FBGA, FPGA, SOC, DDR2, CPLD and MICRO PROCESSOR AND CONTROLLER based other SMD and through hole components.
- Designed chip test interface boards like Probe cards, Load boards, Dut boards and Motherboards as per IPC.
- Handled Ground Shielding on special nets.
- Used Split Power Planes technology to reduce the number of overall layers.
- Used Auto Router to evaluate the correctness / efficiency of placement & density of routing.
- Manual routing & DFM is followed with post routing cleanup.
- Performed design constraint requirements (i.e. Differential Routing, Controlled Lengths/Delay, Cross talk Control, etc.).
- Best Practices IPC Standards and Conventions.
- Experience in Through-Hole, Blind and Buried vias and Microvias.
- Designed boards of following clients:
  - INTEL (TIU, SVIU, VVIU & CVIU templates)
  - > INTERSIL
  - > SPECTRALINEAR
  - CYPRESS
  - NATIONAL SEMICONDUCTOR
  - SYNAPTICS
  - MARVELL
- PCB design experience on the following applications:
  - High-speed telecom boards
  - High-speed data acquisition cards
  - Medical Systems
  - Switch mode power supply
  - > Flexible cards
  - > RF cards
  - > Test Equipment

#### **Tester Exposure:**

- Credence (SC312, SC212, Duo, Quartet, Vistavision).
- Agilent (83K, 93K, V4400, V5400).
- Teradyne (J971, J973, J750 Universal, Catalyst).

### **Essential duties and Responsibilities:**

- Works closely with Hardware engineers to implement design requirements, rules and constraints; Work with mechanical, safety, EMC and manufacturing engineers to ensure that standards for product ability, approval and compliance are met.
- Participate in design reviews and provide PCB design schedule input.
- Develop and maintain PCB CAD footprint.
- Package electrical and mechanical design data, identifying missing data, schematic errors and inconsistencies in mechanical data.
- Develop PCB layer Stack-up.
- Perform placement and routing of high complexity multi-layer printed circuit boards working from design requirements.
- Target 100% DFT test point coverage.
- Meet the DFM requirements.
- Perform DRC.
- Document design package from PCB database, developing fabrication and assembly drawings.
- Oversee PCB design reviews, checks and approvals processes prior to design release.
- Help resolve technical queries from PCB fabricators and contract manufacturers.

#### **Software Exposure:**

Operating System : Windows, Linux.Languages : C, C++, Core Java.

Web technologies : Html, Php, Css, Java script, Jquery.
Database : MySQL, PHPMyAdmin, Oracle10g.

Framework: : .Net, Joomla